

4 Amps, 600Volts

N-CHANNEL MOSFET

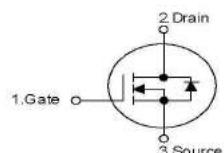
■ DESCRIPTION

The SI4N60 is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies .PWM motor controls, high efficient DC to DC converters and bridge circuits.

■ FEATURES

- $R_{DS(ON)}=2.5\Omega @V_{GS}=10V$
- Ultra Low gate charge(typical 15.0nC)
- Low reverse transfer capacitance($C_{RSS}=\text{typical } 8.0\text{pF}$)
- Fast switching capability
- Avalanche energy specified
- Improved dv/dt capability,high ruggedness

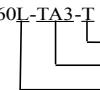
■ SYMBOL



■ ORDERING INFORMATION

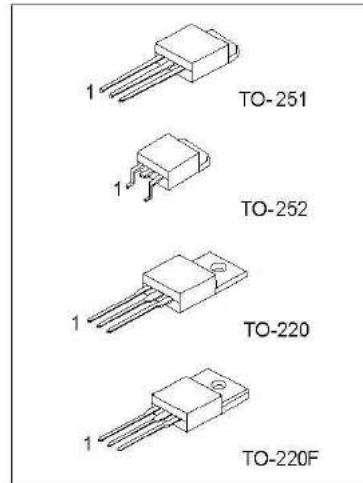
Order Number		Package	Pin Assignment			Packing
Normal	Lead Free Plating		1	2	3	
4N60-TA3-T	4N60L-TA3-T	TO-220	G	D	S	Tube
4N60-TF3-T	4N60L-TF3-T	TO-220F	G	D	S	Tube
4N60-TM3-T	4N60L-TM3-T	TO-251	G	D	S	Tube
4N60-TN3-R	4N60L-TN3-R	TO-252	G	D	S	Tape Reel
4N60-TN3-T	4N60L-TN3-T	TO-252	G	D	S	Tube

Note:Pin Assignment: G:Gate D:Drain S:Source

 (1) Packing Type (2) Package Type (3) Lead Plating	(1) T:Tube,R:Tape Reel
	(2) TA3:TO220,TF3:TO-220F,TM3:TO-251,TN3:TO-252
	(3)L:Lead Free Plating Blank: Pb/Sn

■ ABSOLUTE MAXIMUM RATINGS ($T_c=25^\circ C$, unless otherwise specified)

PARAMETER		SYMBOL	PATINGS	UNIT
Drain-Source Voltage		V_{DSS}	600	V
Gate-Source Voltage		V_{GSS}	± 30	V
Avalanche Current(Note 2)		I_{AP}	4.4	A
Drain Currentet Continuous	$T_c=25^\circ C$	I_D	4.0	A
Drain Current Pulsed(Note 2)		I_{DP}	16	A



*Pb-free plating product number: 4N60



N-CHANNEL MOSFET

SI4N60

Avalanche Energy	Repetitive(Note 2)	E_{AR}	260	mJ
	Single Pulse(Note 3)	E_{AS}	10.6	mJ
Peak Diode Recovery dv/dt(Note 4)		dv/dt	4.5	v/ns
Total Power Dissipation	$T_c=25^\circ\text{C}$	P_D	75	W
	Derate above 25°C		0.59	W/°C
Junction Temperature		T_J	+150	°C
Storage Temperature		T_{STG}	-55~+150	°C

Note:1.Absolute maximum ratings are those values beyond which the device could be permanently damaged

Absolute maximum ratings are stress ratings only and functional device operation is not implied

2.Repetitive Rating:Pulse width limited bu maximum junction temperature

■ THERMAL DATA

PARAMETER	PACKAGE	SYMBOL	RATINGS	UNIT
Thermal Resistance Junction-Ambient	TO-251	θ_{JA}	83	°C/W
	TO-252		83	
	TO-220		62.5	
	TO-220F		62.5	
Thermal Resistance Junction-Case	TO-251	θ_{JC}	2.5	°C/W
	TO-252		2.5	
	TO-220		1.18	
	TO-220F		3.47	

■ ELECTRICAL CHARACTERISTICS($T_j=25^\circ\text{C}$, unless Otherwise specified.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}, I_D=250\text{ }\mu\text{A}$	600			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$			10	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=30\text{V}, V_{DS}=0\text{V}$			100	nA
		$V_{GS}=-30\text{V}, V_{DS}=0\text{V}$			-100	nA
Breakdown Voltage Temperature	$\Delta BV_{DSS}/\Delta T_J$	$I_D=250\text{ }\mu\text{A}$		0.6		V/°C
On Characteristics						
Gate Threshold Voltage	$V_{GS(\text{TH})}$	$V_{DS}=V_{GS}, I_D=250\text{ }\mu\text{A}$	2.0		4.0	V
Static Drain-Source On-Resistance	$R_{DS(\text{ON})}$	$V_{DS}=10\text{V}, I_D=2.0\text{A}$			2.5	Ω
Forward Transconductance	g_{FS}	$V_{DS}=100\text{V}, I_D=2.4\text{A}(\text{Note 1})$	2.9			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		520	670	pF
Output Capacitance	C_{OSS}			70	90	pF
Reverse Transfer Capacitance	C_{RSS}			8	11	pF

■ ELECTRICAL CHARACTERISTICS(Cont.)

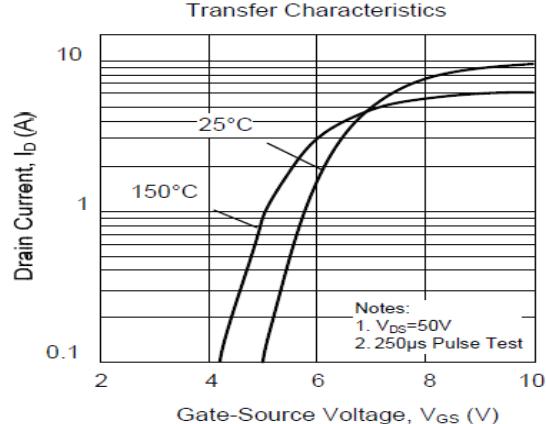
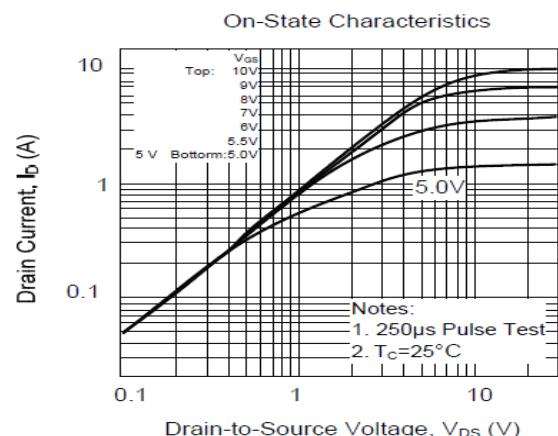
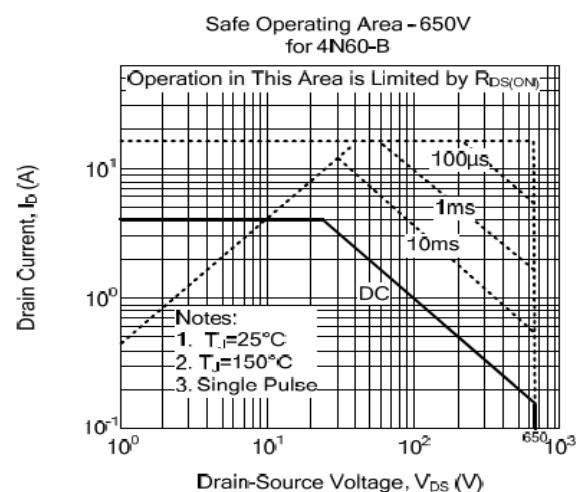
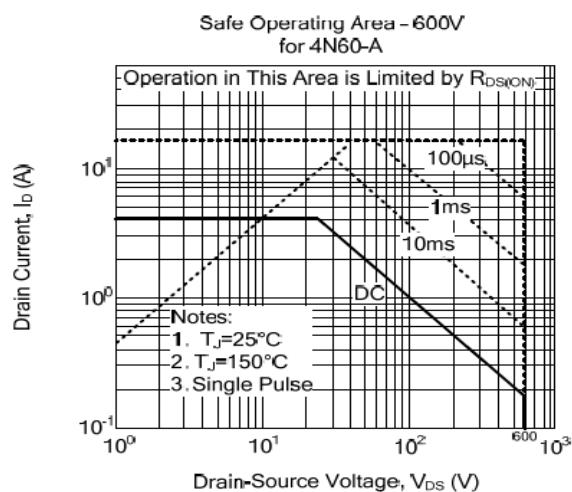
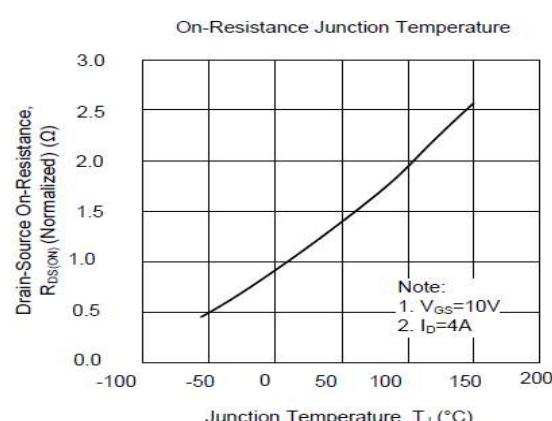
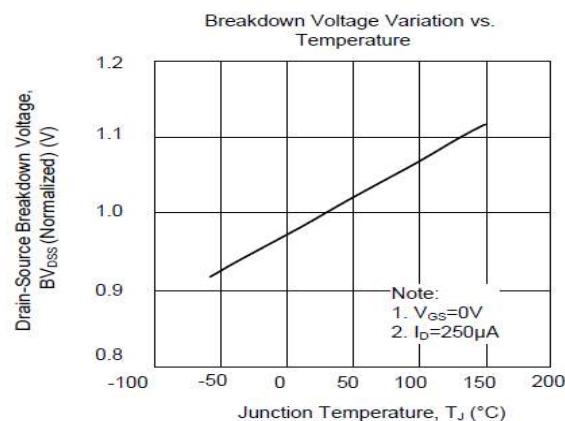
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Switching Characteristics						
Turn-On Delay Time	$t_{D(\text{ON})}$			13	35	ns
Rise Time	t_R	$V_{DD}=300\text{V}, I_D=4.0\text{A}, R_G=25\text{ }\Omega$ (Note 1, 2)		45	100	ns
Turn-Off Delay Time	$t_{D(\text{OFF})}$			25	60	ns
Fall Time	t_F			35	80	ns
Total Gate Charge	Q_G	$V_{DS}=480\text{V}, V_{GS}=10\text{V}, I_D=4.0\text{A}$		15	20	nC

Gate-Source Charge	Q_{GS}	(Note1,2)		3.4		nC
Gate-Drain Charge	Q_{GD}			7.1		nC
Drain-Source Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=4.4A$			1.4	V
Continuous Drain-Source Current	I_{SD}				4.4	A
Pulsed Drain-Source Current	I_{SM}				17.6	A
Reverse Recovery Time	t_{RR}	$V_{GS}=0V, I_{SD}=4.4A,$ $dI/dt=100A/\mu A$		250		ns
Reverse Recovery Charge	Q_{RR}			1.5		μC

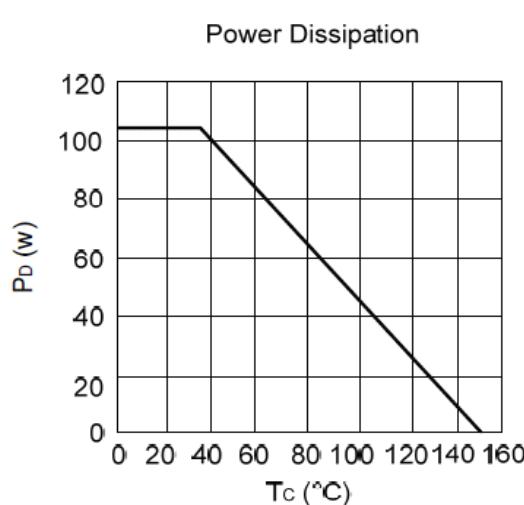
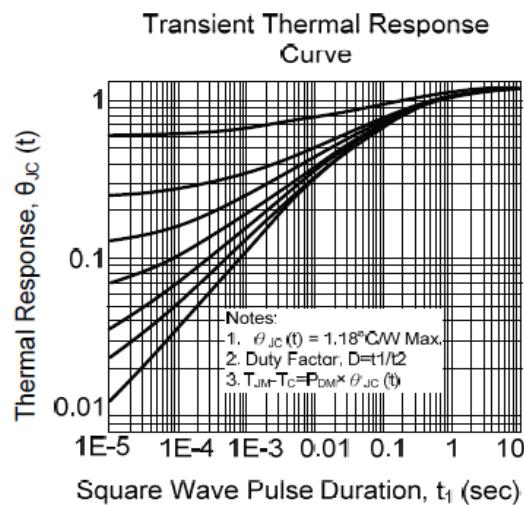
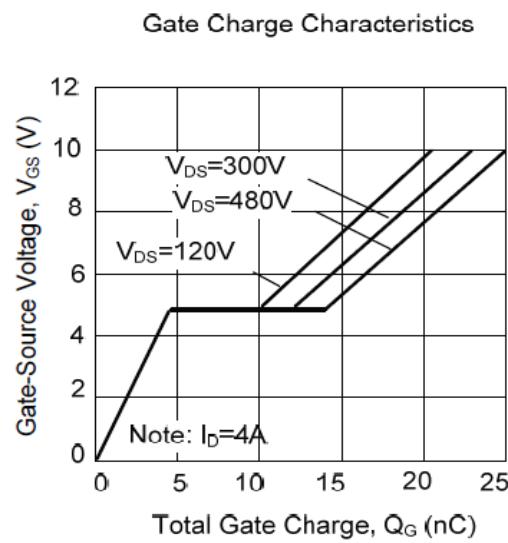
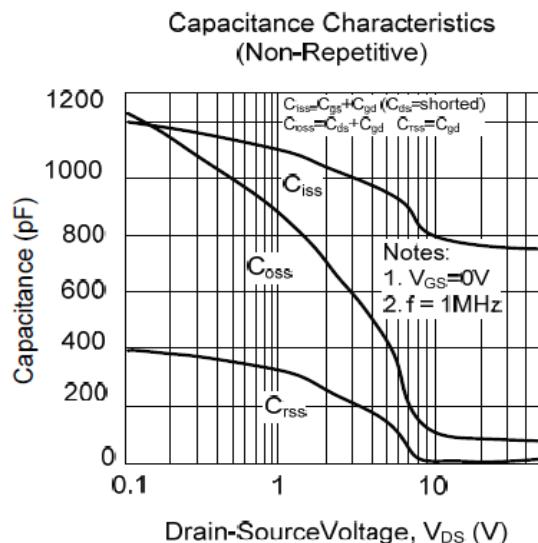
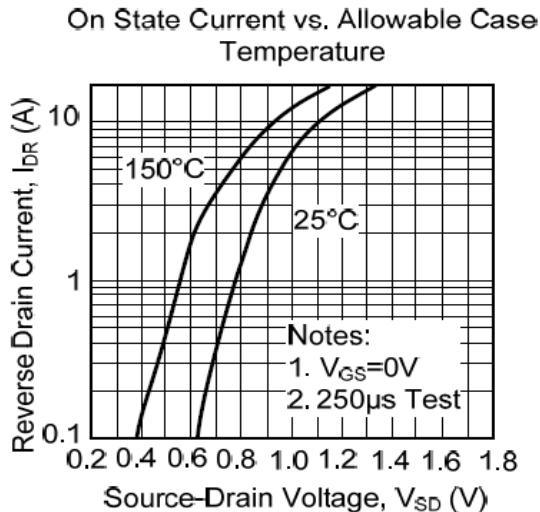
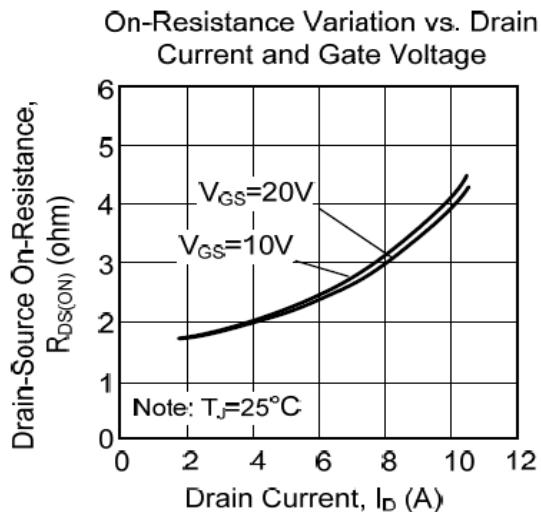
Note1: Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$

2. Essentially Independent of Operating Temperature

TYPICAL CHARACTERISTICS



■ TYPICAL PERFORMANCE CHARACTERISTICS(cont)



■ **TYPICAL CHARACTERISTICS(cont)**

Maximum Drain Current vs. Case Temperature

